

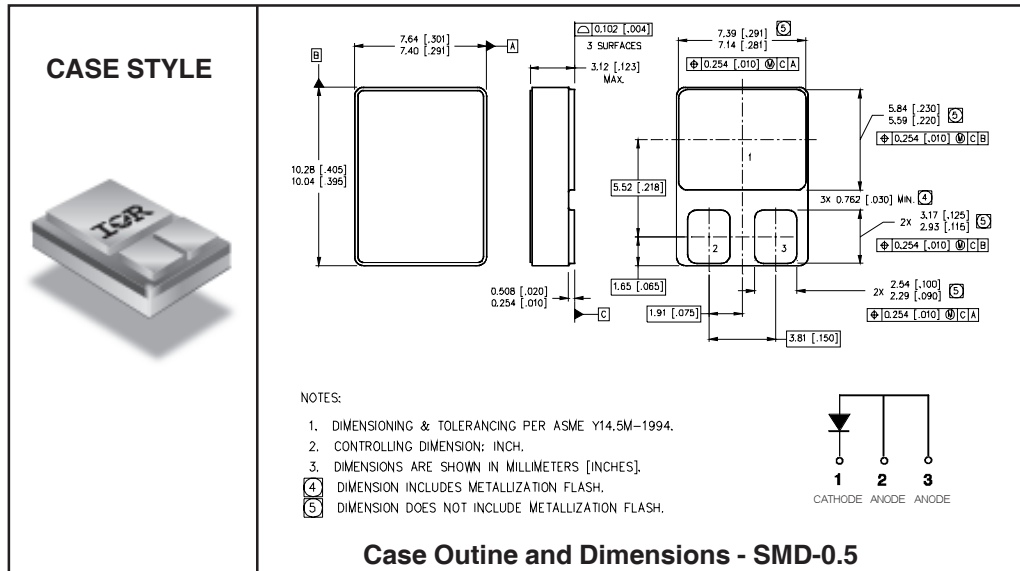
**Major Ratings and Characteristics**

Characteristics	1N7078U3	Units
$I_{F(AV)}$	30	A
$V_{RRM}$	30	V
$I_{FSM}$ @ tp = 8.3ms half-sine	150	A
$V_F$ @ 30Apk, $T_J = 125^\circ\text{C}$	0.57	V
$T_J, T_{STG}$ Operating and Storage	-65 to 150	$^\circ\text{C}$

**Description/Features**

The 1N7078U3 center tap Schottky rectifier has been expressly designed to meet the rigorous requirements of HiRel environments. It is packaged in the hermetic surface mount SMD-0.5 ceramic package. The device's forward voltage drop and reverse leakage current are optimized for the lowest power loss and the highest circuit efficiency for typical high frequency switching power supplies and resonant power converters. Full MIL-PRF-19500 quality conformance testing is available on source control drawings to TX, TXV and S quality levels.

- Hermetically Sealed
- Low Forward Voltage Drop
- High Frequency Operation
- Guard Ring for Enhanced Ruggedness and Long Reliability
- Surface Mount
- Lightweight
- ESD Rating: Class NS per MIL-STD-750, Method 1020



**Voltage Ratings**

Part number	1N7078U3
V <sub>R</sub> Max. DC Reverse Voltage (V)	30
V <sub>RWM</sub> Max. Working Peak Reverse Voltage (V)	

**Absolute Maximum Ratings**

Parameters	Limits	Units	Conditions
I <sub>F(AV)</sub> Max. Average Forward Current See Fig. 5	30	A	50% duty cycle @ T <sub>C</sub> = 105°C, square waveform
I <sub>FSM</sub> Max. Peak One Cycle Non - Repetitive Surge Current	150	A	@ t <sub>p</sub> = 8.3 ms half-sine

**Electrical Specifications**

Parameters	Limits	Units	Conditions
V <sub>FM</sub> Max. Forward Voltage Drop See Fig. 1①	0.58	V	@ 15A
	0.61	V	@ 20A
	0.67	V	@ 30A
	0.51	V	@ 10A
	0.55	V	@ 20A
	0.62	V	@ 30A
	0.41	V	@ 15A
	0.47	V	@ 20A
I <sub>RM</sub> Max. Reverse Leakage Current See Fig. 2①	1.0	mA	T <sub>J</sub> = 25°C
	150	mA	T <sub>J</sub> = 125°C
			V <sub>R</sub> = Rated V <sub>R</sub> ②
C <sub>T</sub> Max. Junction Capacitance	2000	pF	V <sub>R</sub> = 5V <sub>DC</sub> ( 1.0 MHz, 25°C)②
L <sub>S</sub> Typical Series Inductance	4.8	nH	Measured from center of cathode pad to center of anode pad

**Thermal-Mechanical Specifications**

Parameters	Limits	Units	Conditions
T <sub>J</sub> Max. Junction Temperature Range	-65 to 150	°C	
T <sub>stg</sub> Max. Storage Temperature Range	-65 to 150	°C	
R <sub>thJC</sub> Max. Thermal Resistance, Junction to Case	1.6	°C/W	DC operation See Fig. 4
wt Weight (Typical)	1.0	g	
Die Size (Typical)	115X170	mils	
Case Style	SMD-0.5		

① Pulse Width &lt; 300μs, Duty Cycle &lt; 2%

② Pins 2 and 3 externally tied together

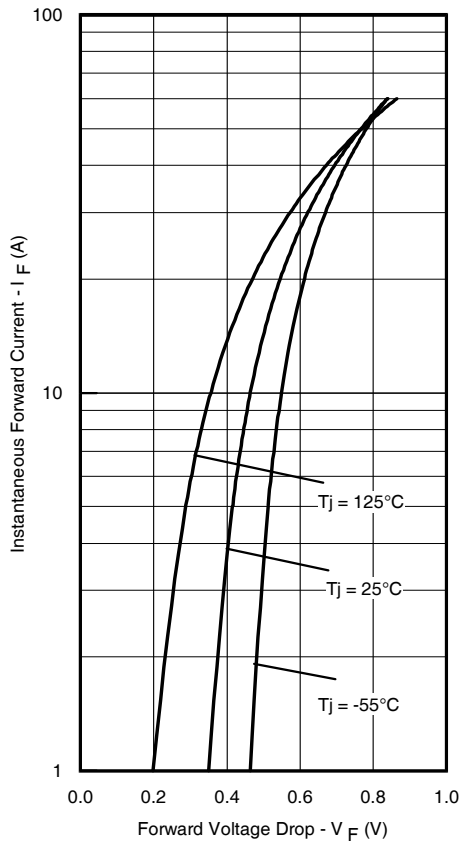


Fig. 1 - Max. Forward Voltage Drop Characteristics

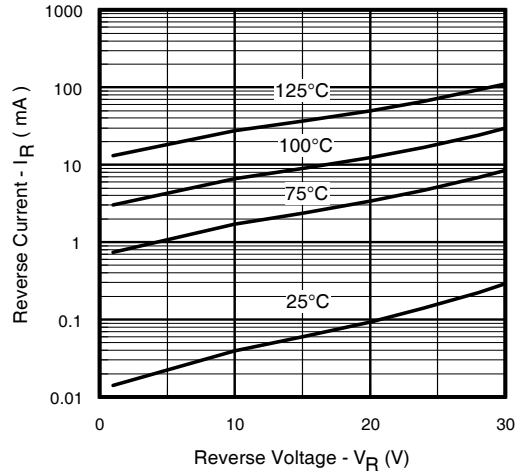


Fig. 2 - Typical Values of Reverse Current Vs. Reverse Voltage

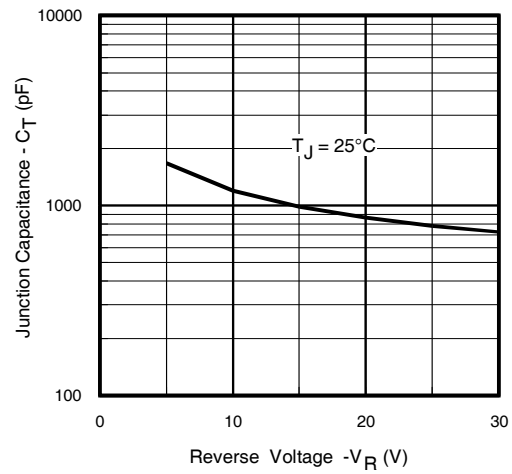


Fig. 3 - Typical Junction Capacitance Vs. Reverse Voltage

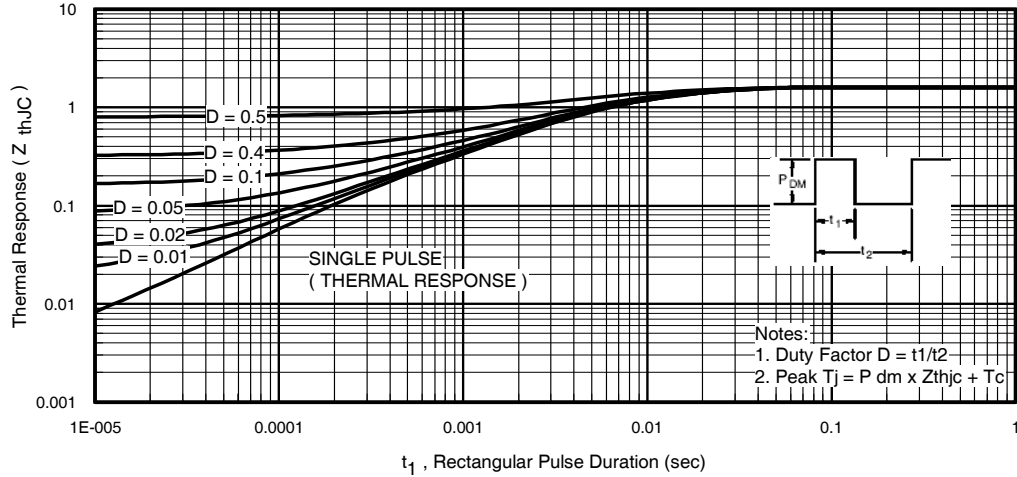


Fig. 4 - Max. Thermal Impedance  $Z_{thJC}$  Characteristics (Per Leg)

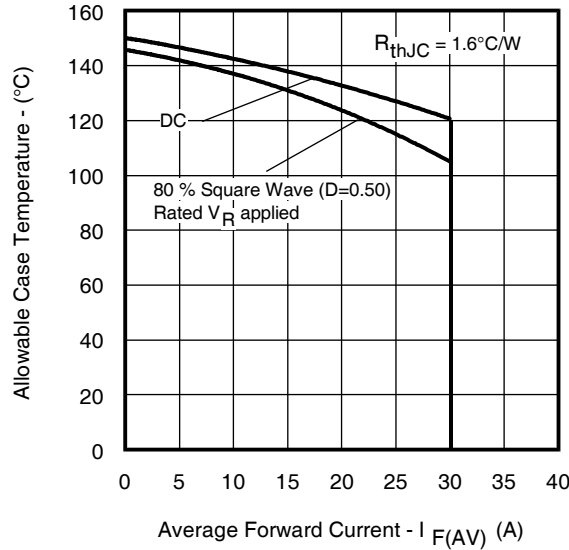


Fig. 5 - Max. Allowable Case Temperature Vs. Average Forward Current